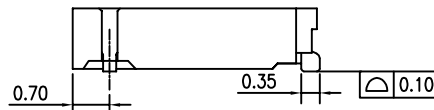
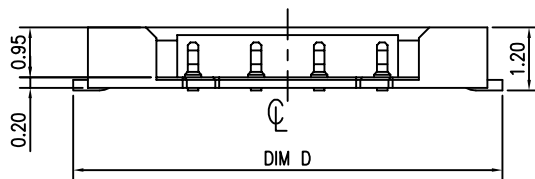
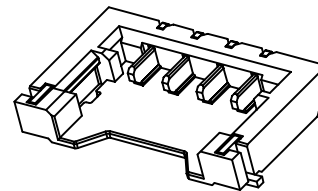


RECOMMENDED PCB LAYOUT
(GENERAL TOLERANCE ±0.05)
(TOP VIEW)



NOTES:

1. MATERIAL:
 - 1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP; UL94V-0.
 - 1.2 CONTACT: COPPER ALLOY.
 - 1.3 FITTING NAIL: COPPER ALLOY
2. FINISH:
 - 2.1 TERMINAL:
 - T: 50u" MIN. NICKEL UNDERPLATING OVERALL. GOLD FLASH ON CONTACT AREA.
 - 10u" MIN. GOLD ON CONTACT AREA.
 - D: 50u" MIN. NICKEL UNDERPLATING OVERALL. 30u" MIN. GOLD ON CONTACT AREA.
 - W: 50u" MIN. NICKEL UNDERPLATING OVERALL. 3u" MIN. GOLD ON CONTACT AREA.
 - 2.2 FITTING NAIL:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 100u" MIN. MATT TIN PLATING OVERALL.
3. SPEC. PLS. REFER TO SPEC-51269-XXXX-XXX
4. THE PACKING DRAWING PLS. REFER TO 51269-XXXX-XX-TRP OR 51269-XXXX-U-TRP
5. PRAT NO:

51269-XXX X X-XXX	XXX Halogen Free	PACKING
001	HF	51269-XXXX-XX-TRP
003	HF	51269-XXXX-G-TRP
004	HF	51269-XXXX-U-TRP

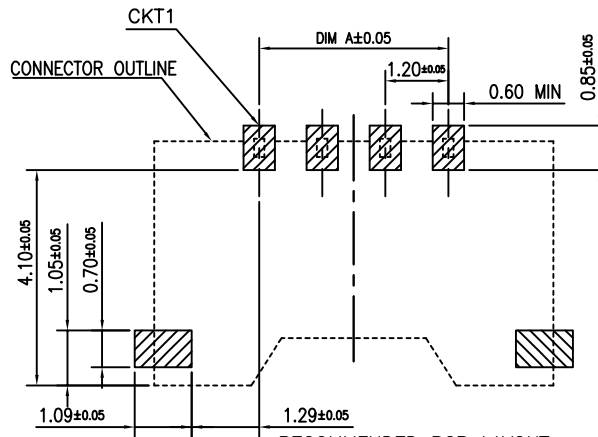
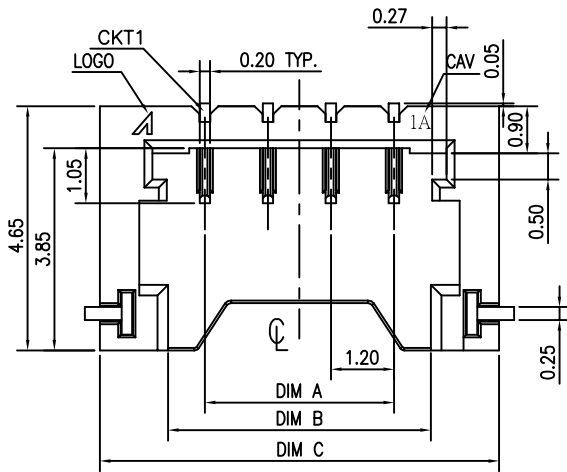
NO OF CKT

PACKING
0: TAPE & REEL

PLATING
1: GOLD FLASH
T: 10u" GOLD ON CONTACT
D: 30u" GOLD ON CONTACT
W: 3u" GOLD ON CONTACT

CKT	Dim A	Dim B	Dim C	Dim D
2	1.2	2.6	5.2	5.8
3	2.4	3.8	6.4	7.00
4	3.6	5.0	7.6	8.20
5	4.8	6.2	8.8	9.40
6	6.0	7.4	10.0	10.60
9	9.6	11.0	13.6	14.20

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ	DRAWN BY Sun, Ya Jie	DATE 23'/01/11	
GENERAL TOLERANCES (UNLESS SPECIFIED)	CHECKED BY Xu, Zhi Yong	DATE 23'/01/11	
X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY Xu, Zhi Yong	DATE 23'/01/11	TITLE 1.2mm PITCH WTB WAFER CONNECTOR
UNITS mm	SCALE 1 : 1	SHEET NO. 1 OF 2	REV K
			REFQ NO. N/A
			DWG NO. 51269-XXXX-XXX

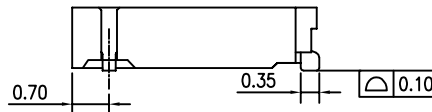
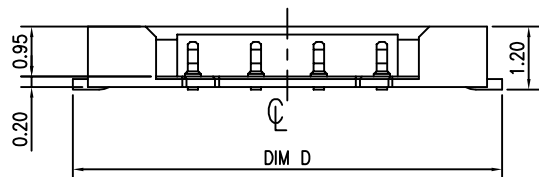
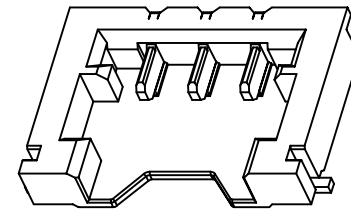


RECOMMENDED PCB LAYOUT
(GENERAL TOLERANCE ±0.05)
(TOP VIEW)

NOTES:

1. MATERIAL:
 - 1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP; UL94V-0.
 - 1.2 CONTACT: COPPER ALLOY.
 - 1.3 FITTING NAIL: COPPER ALLOY
2. FINISH:
 - 2.1 TERMINAL:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL. GOLD FLASH ON CONTACT AREA.
 - 2.2 FITTING NAIL:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 100u" MIN. MATT TIN PLATING OVERALL.
3. SPEC. PLS. REFER TO SPEC-51269-XXXX-XXX
4. THE PACKING DRAWING PLS. REFER TO 51269-XXXX-XX-TRP
5. PRAT NO:

51269-XXX	X	X-XXX	
			002
NO OF CKT		PLATING	1: GOLD FLASH
		PACKING	0: TAPE & REEL



CKT	Dim A	Dim B	Dim C	Dim D
3	2.4	3.8	6.4	7.00

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ	DRAWN BY Sun, Ya Jie	DATE 23'/01/11		
	CHECKED BY Xu, Zhi Yong	DATE 23'/01/11		
GENERAL TOLERANCES (UNLESS SPECIFIED)	APPROVED BY Xu, Zhi Yong	DATE 23'/01/11	TITLE 1.2mm PITCH WTB WAFER CONNECTOR	
	X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	UNITS mm	SIZE A4	REF. NO. N/A
	SCALE 1 : 1	SHEET NO. 2 OF 2	REV K	DWG NO. 51269-XXXX-XXX